



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTS3050TF	Issued	24. February 2022
MA#	MA005700566		
Package	PG-TO252-3-313	Weight*	317.44 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.162	0.37	0.37	3662	3662
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		464	
	non noble metal	copper	7440-50-8	147.096	46.32	46.38	463380	463983
wire	non noble metal	aluminium	7429-90-5	1.183	0.37	0.37	3727	3727
encapsulation	inorganic material	zinc oxide	1314-13-2	1.421	0.45		4477	
	miscellaneous	miscellaneous	-	7.106	2.24		22384	
	plastics	epoxy resin	-	21.317	6.72		67151	
	inorganic material	silicon dioxide	60676-86-0	112.267	35.37	44.78	353663	447675
lead finish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11782	11782
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4475	4486
solder	non noble metal	tin	7440-31-5	0.027	0.01		84	
	noble metal	silver	7440-22-4	0.033	0.01		105	
	non noble metal	lead	7439-92-1	1.271	0.40	0.42	4005	4194
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.04	6.05	60413	60491
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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